

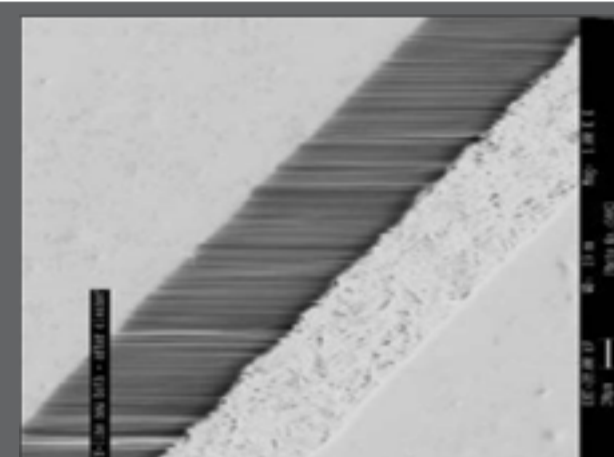
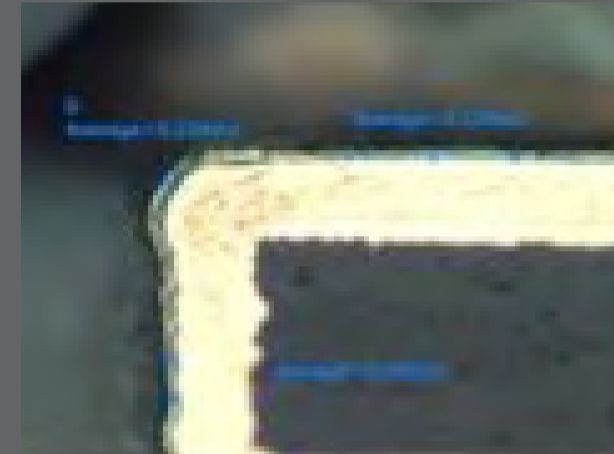
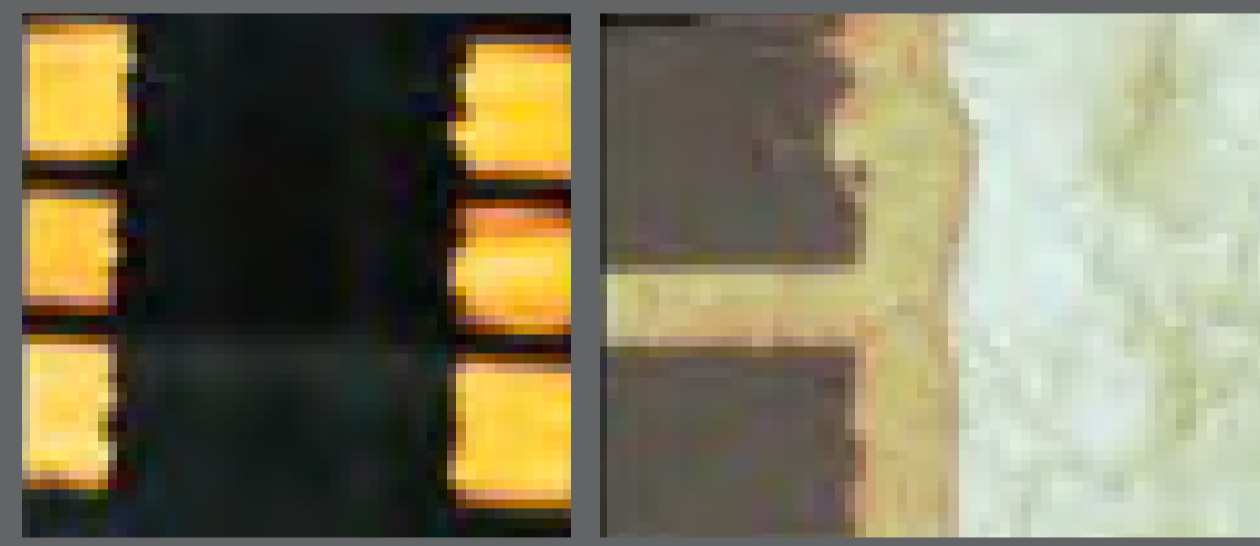


# Green Products | 绿色产品

## NP/NPE free (meet REACH requirement) 不含壬基酚 (符合欧盟REACH环保规范)

NP (Nonyl Phenol) / NPE (Nonyl Phenol Ethoxylate) are generally used as surfactant. However, due to health and environmental hazards, NP/NPE has been banned in EU.

壬基酚一般用作介面活性剂。然而，基于对健康及环境的危害，壬基酚已被欧盟禁止使用。

Product 产品	Features and Benefits 特性及效益	
RONACLEAN™ EVP 200 Cleaner Series	<ul style="list-style-type: none"> <li>• One component acid cleaner 单一成份酸性清洁剂</li> <li>• Excellent cleaning performance for dry film and other residues 针对干膜及其他残渣，具有绝佳的清洁能力</li> <li>• Capable of pattern process without damaging dry film 适用于线路镀铜制程，同时并不会损害干膜</li> </ul>	 <p>Excellent detergency without damaging dry film 绝佳的清洁能力，且不损害干膜</p>
RONASTAN™ ECX Tin Plating	<ul style="list-style-type: none"> <li>• Cost Effective 成本效益优势</li> <li>• Environmentally-friendly 环保导向</li> <li>• Higher alkaline etching resistance 高抗碱性能力</li> <li>• Robustness to organic contamination 有机污流具有高容忍度</li> </ul>	 <p>Excellent coverage and resistance 绝佳的锡层覆盖及抗蚀刻能力</p>
CRIMSON™ Sensitizer 5123M-1	<ul style="list-style-type: none"> <li>• Excellent and uniform coverage on both glass fiber and resin 在玻璃纤维及树脂上，皆有绝佳且一致的覆盖性</li> <li>• Provide optimum Pd adsorption for all laminate and dielectric materials yielding complete electroless copper coverage 在不同板材上，提供最优化之钯吸附量，助于化学沉铜产生完整的覆盖</li> <li>• Excellent reliability performance 绝佳的信赖度表现</li> </ul>	 <p>Excellent coverage and reliability performance 绝佳的覆盖性及信赖度表现</p>
CIRCUPOSIT™ Conditioner 3323A		

## EDTA free 不含乙二酸四乙胺

EDTA (Ethylenediaminetetraacetic acid) is a chelating agent. It captures abundant metal ions in solution but itself is not easy to be degraded, making it a persistent organic pollutant.

EDTA作为螯合剂。它于水溶液中捕捉大量金属离子但本身却不易被分解，使其成为长期有机污染物

Product 产品	Features and Benefits 特性及效益	
CIRCUPOSIT™ ADV 8550 Electroless Copper	<ul style="list-style-type: none"> <li>• High speed deposition with excellent bath stability 沉积速率快且槽液稳定性亦高</li> <li>• Pure Copper metal deposition without affect to for Flash etching speed 纯铜金属沉积，不影响后段线路蚀刻速率</li> </ul>	 <p>Excellent Plating uniformity on Microvia 优良的沉积均匀度于盲孔内</p>
CIRCUPOSIT™ 328 Electroless Copper	<ul style="list-style-type: none"> <li>• High-yield, "thin" electroless copper, tartrate-based 高附载，薄化学沉铜，酒石酸系统</li> <li>• Excellent plating coverage and copper-to-copper bonds achieved with all electroplate coppers 绝佳的化学铜镀层覆盖性，使其与不同的电镀铜，皆可达成良好的铜与铜连结力</li> </ul>	 <p>Excellent coverage on PI 在PI上具有绝佳的覆盖能力</p>
AUROELECTROLESS™ SMT 525G	<ul style="list-style-type: none"> <li>• Low gold content operation with 0.5- 1.0g/L 低金含量操作，金浓度为0.5-1.0g/L</li> <li>• Low gold porosity deposition with very good Ni coverage to avoid corrosion in post treatment process 低疏孔性的化学金层，良好且致密地覆盖于镍层之上，可避免后制程的腐蚀及攻击</li> <li>• Compatible with ENEPIG and Selective ENIG process 适用于化学镍钯金及选择性化学镍金制程</li> </ul>	 <p>No Ni corrosion 无镍层腐蚀</p>

## Formaldehyde free/ HCHO free 不含甲醛

Formaldehyde is a strong reducing agent. Nonetheless, it causes health damage by inhalation.

甲醛为一强还原剂。不过经由吸入会对人体造成健康危害。

Product 产品	Features and Benefits 特性及效益
CRIMSON™ Direct Plating	The leading palladium-based direct plate system in horizontal process that creates a stable sulfide conversion coating 硫化钯系统的直接电镀制程，适用于水平线，并可产生稳定镀层
CONDUCTRON™ Direct Plating	Unique palladium-based system that creates the conductive direct plate coating with fine quality and high reliability 独特的钯系统直接电镀制程，可产生良好品质及高信赖度的镀层

